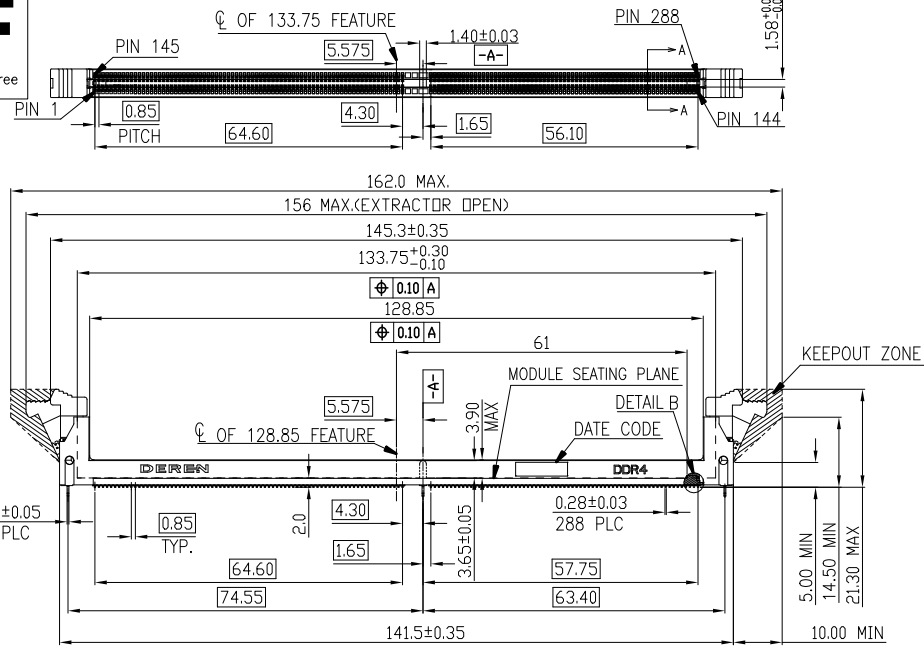
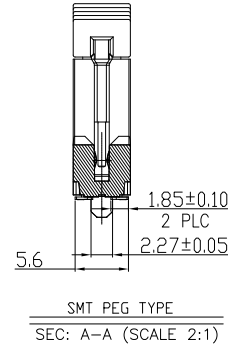
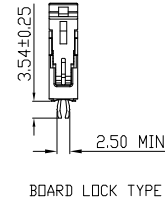
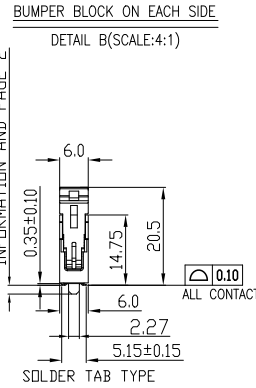


HF
Halogen Free



SEE THE PART NUMBER INFORMATION AND PAGE 2



REV	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL ISSUE	12/28'23	Joe Lam

NOTES:

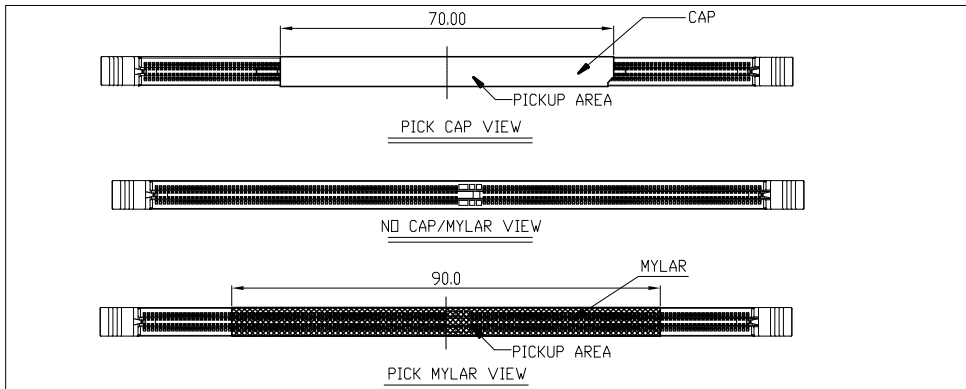
- PRODUCT MUST MEET CONTROLLED SUBSTANCES SPEC. ROHS 2.0
- 1. MATERIAL:
 - 1.1 HOUSING: NYLON , UL94V-0; COLOR: SEE P/N INFORMATION.
 - 1.2 EXTRACTOR: NYLON ,UL94V-0; COLOR: SEE P/N INFORMATION.
 - 1.3 CONTACT: COPPER ALLOY .
 - 1.4 FORK LOCK: STAINLESS STEEL.
 - 1.5 METAL SHEET: STAINLESS STEEL
- 2. FINISH:
 - 2.1 CONTACT:
 - GOLD PLATING(SEE SEE P/N INFORMATION.) ON CONTACT AREA.
 - 2.0um[80u"] MIN. MATTE-TIN PLATING ON SOLDER TAIL AREA.
 - 2.25um[90u"] MIN. NICKEL ON CONTACT AREA,
 - 1.27um[50u"] MIN. NICKEL ON OTHER AREA.
 - 2.2 FORK LOCK:
 - MATTE TIN PLATING 80u"Min ON SOLDER TAIL AREA.
 - 50u" MIN. NICKEL UNDERPLATING OVERALL.
- 3. REFLOW SOLDER CAPABLE TO 260°C MAX. 10S.
- 4. MECHANICAL SPECIFICATION:
 - MATING FORCE: 106.8N MAX.
 - UNMATING FORCE: 19.77N MIN.
 - DURABILITY: 25 MATING AND UNMATING CYCLES
- 5. ELECTRICAL SPECIFICATION
 - CONTACT RESISTANCE: INITIAL:10 MILLIOHMS MAX.,
 - CONTACT RESISTANCE: FINAL: CHANGE 10 MILLIOHMS MAX..
 - CURRENT RATING: 0.75AMPS MAX.
 - INSULATION RESISTANCE: 1 MEGOHMS MIN. AT 500VAC
 - DIELECTRIC WITHSTAND VOLTAGE: 500VAC MIN. FOR ONE MINUTE.
- 6. ENVIRONMENT SPECIFICATION
 - OPERATING TEMPERATURE: -55°C TO +85°C.
 - SOLDERABILITY: PASSED PER EIA-364-52, CLASS 2, CATEGORY 3.
 - VIBRATION: PASSED PER EIA-364-28.
 - HUMIDITY: PASSED PER EIA-364-31.
 - THERMAL SHOCK: PASSED PER EIA-364-32.
 - MECHANICAL SHOCK: PASSED PER EIA-364-27.
- 7. PART NUMBER INFORMATION:

568QD0-001 H X X X X

- GREEN CODE:
 - H: HALOGEN FREE
- PLATING CODE:
 - 1:GOLD FLASH
 - 2:GOLD 15u"
 - 3:GOLD 30u"
- HOUSING COLOR CODE:
 - 1: BLACK DEREN LOGO
 - 2: WHITE DEREN LOGO
 - 3: BLUE DEREN LOGO
 - 4: GREY DEREN LOGO
 - 5: BLACK NO LOGO
 - 6: WHITE NO LOGO
 - 7: BLUE NO LOGO
 - 8: GREY NO LOGO
- EXTRACTOR COLOR CODE:
 - 1: BLACK
 - 2: WHITE
 - 3: BLUE
- PACKAGE & PICKUP CODE:
 - 1: HARD TRAY PACKING,WITH CAP
 - 2: HARD TRAY PACKING,WITHOUT CAP/MYLAR
 - 3: HARD TRAY PACKING, WITH MYLAR
 - 4: SOFT TRAY PACKING,WITH CAP
 - 5: SOFT TRAY PACKING,WITHOUT CAP/MYLAR
 - 6: SOFT TRAY PACKING, WITH MYLAR
- FORK LOCK & DIMM TYPE CODE:
 - 1: THREE SOLDER TAB L=2.0±0.25mm
 - 2: THREE BOARD LOCK
 - 3: ONE BOARD LOCK IN MINDLE , TWO SOLDER TAB L=2.0±0.25mm AT BOTH ENDS
 - 4: ONE SMT PEG IN MINDLE , TWO SOLDER TAB L=2.0±0.25mm AT BOTH ENDS
 - 5: THREE SOLDER TAB L=2.6±0.25mm
 - 6: THREE BOARD LOCK
 - 7: ONE BOARD LOCK IN MINDLE , TWO SOLDER TAB L=2.6±0.25mm AT BOTH ENDS
 - 8: ONE SMT PEG IN MINDLE , TWO SOLDER TAB L=2.6±0.25mm AT BOTH ENDS

RECOMMENDED PCB LAYOUT(TOL:±0.05mm)

NOTE:
RECOMMENDED STENCIL THICKNESS NO LESS THAN 0.18MM



DIM	TOL	DIM	TOL
.x.	±0.35	.x.	±2*
.x	±0.25	.x	±1*
.xx	±0.20		
.xxx	±0.15		



DEREN
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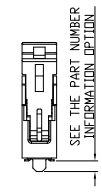
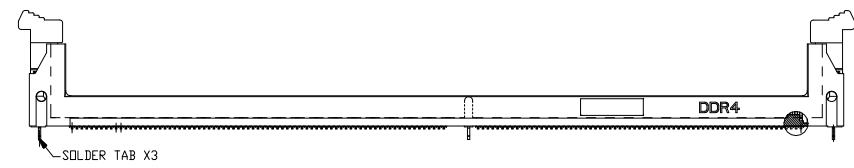
C-DWG:	TY	DATE	TITLE:
SC2107184-1	Joe Lam	12/28'23	DDR4 288PIN SMT BIG EXTRACTOR SOLDER TAB
DESIGN:	Mike Chen	12/28'23	P/N:SEE P/N INFORMATION
CHECK:	Bill Lin	12/28'23	SHEET: 1/4
APPROVAL:			SCALE: 1:1 UNIT: mm

1 2 3 4 5 6 7 8

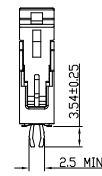
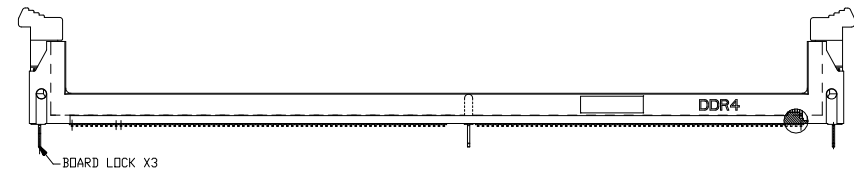
REV	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL ISSUE	12/28'23	Joe Lam

FORK LOCK TYPE :

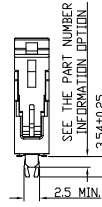
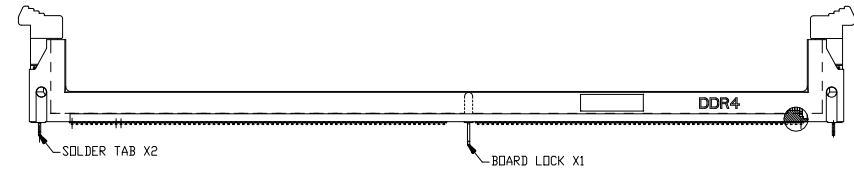
TYPE 1:
THREE SOLDER TAB



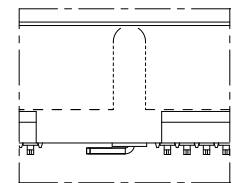
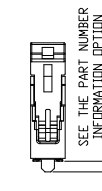
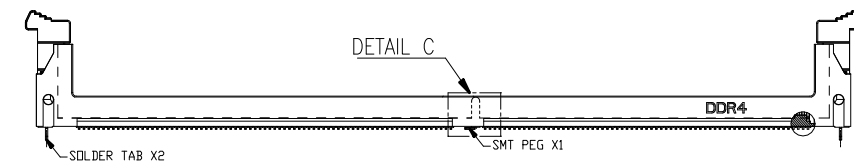
TYPE 2:
THREE BOARD LOCK



TYPE 3:
ONE BOARD LOCK IN MINDDLE ,
TWO SOLDER TAB AT BOTH ENDS



TYPE 3:
ONE SMT PEG IN MINDDLE ,
TWO SOLDER TAB AT BOTH ENDS



DETAIL C(SCALE:4:1)

DIM	TOL	DIM	TOL
x.	±0.35	x.	±2°
.x	±0.25	.x	±1°
.xx	±0.20		
.xxx	±0.15		



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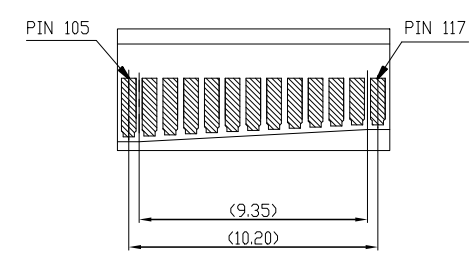
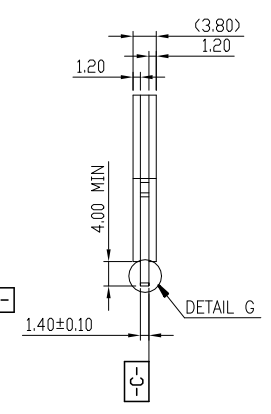
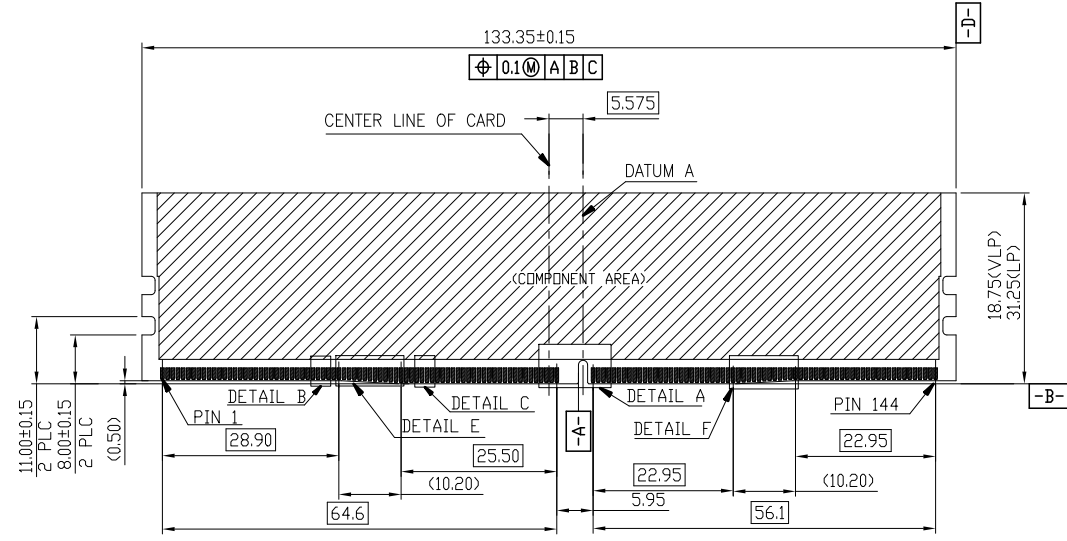
C-DWG:	TY	DATE	TITLE: DDR4 288PIN SMT BIG EXTRACTOR SOLDER TAB
DESIGN:	Joe Lam	12/28'23	P/N:SEE P/N INFORMATION
CHECK:	Mike Chen	12/28'23	SHEET: 2/4
APPROVAL:	Bill Lin	12/28'23	SCALE: 1:1 UNIT: mm

1 2 3 4 5 6 7 8

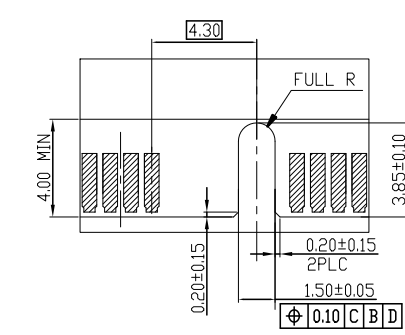
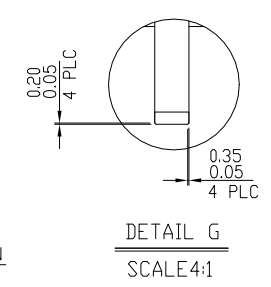
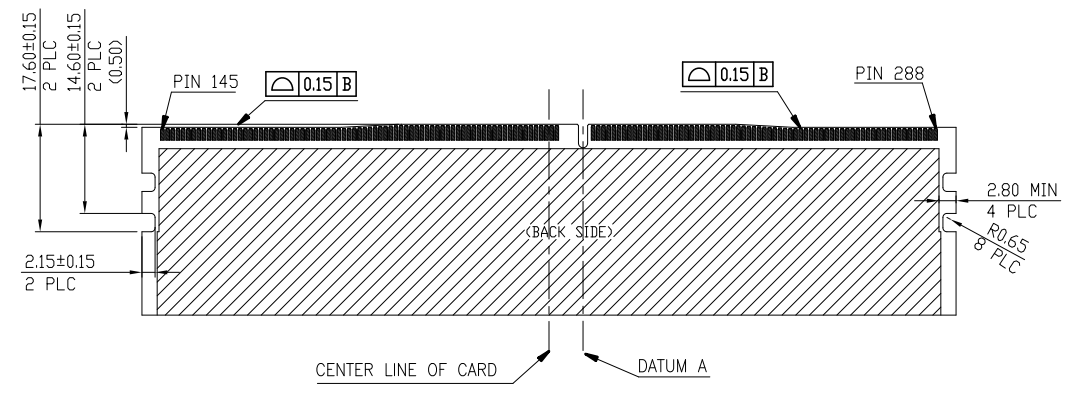
HF

Halogen Free

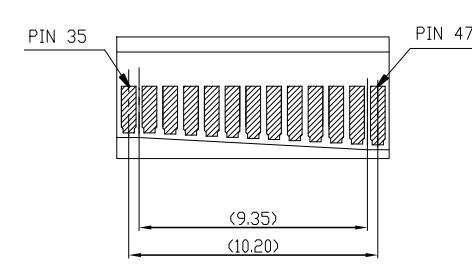
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL ISSUE	12/28'23	Joe Lam



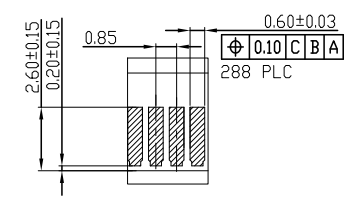
DETAIL F
 SCALE 4:1



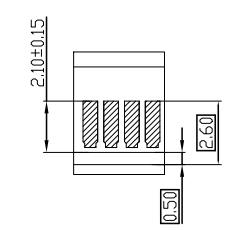
DETAIL A
 SCALE 4:1



DETAIL E
 SCALE 4:1

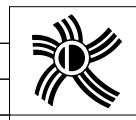


DETAIL C
 SCALE 4:1



DETAIL B
 SCALE 4:1

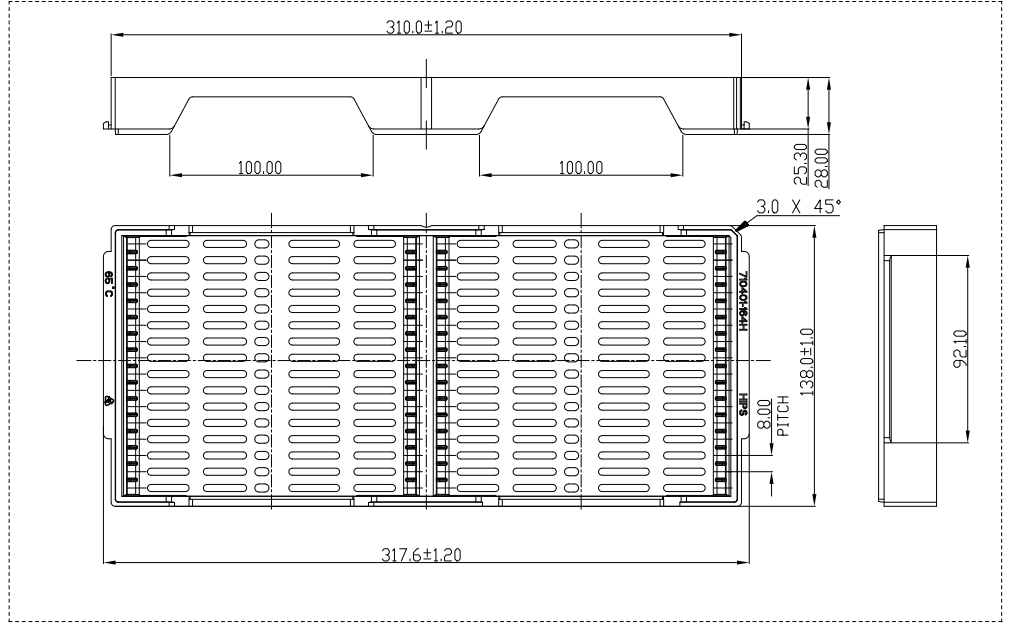
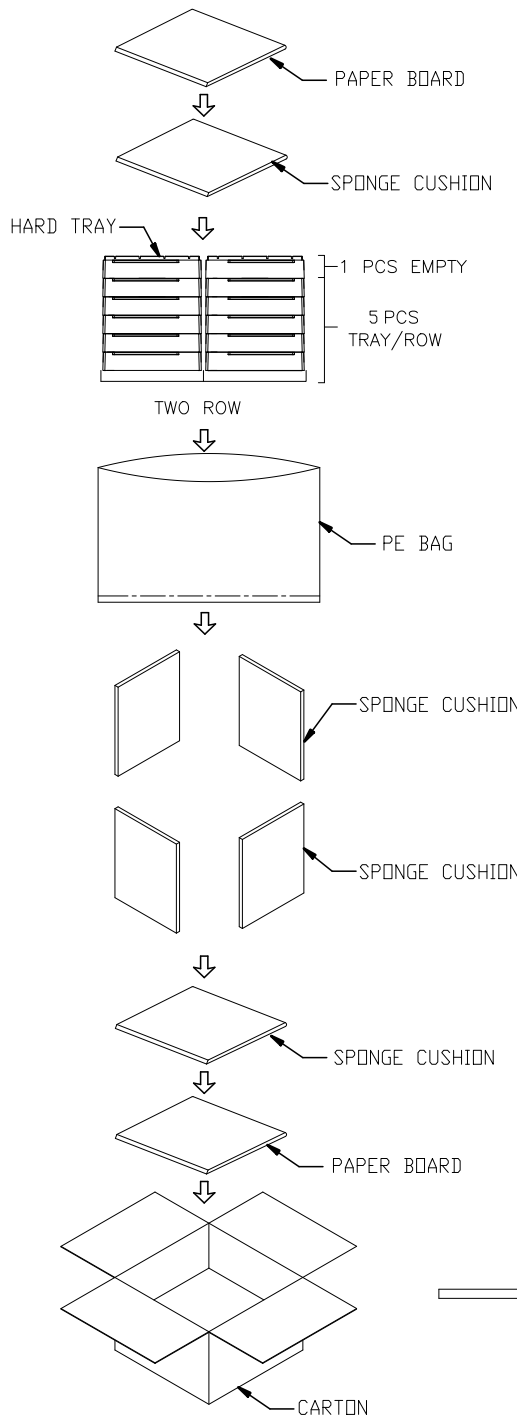
DIM	TOL	DIM	TOL
.x	±0.35	.x	±2*
.x	±0.25	.x	±1*
.xx	±0.20		
.xxx	±0.15		



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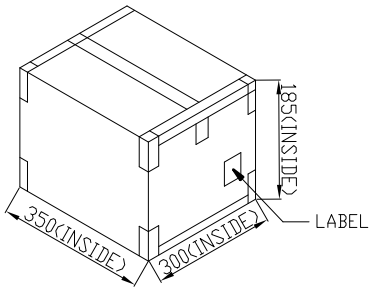
C-DWG:	TY	DATE	TITLE:
SC2107184-1	Joe Lam	12/28'23	DDR4 288PIN SMT BIG EXTRACTOR SOLDER TAB
DESIGN:	Mike Chen	12/28'23	P/N: SEE TABLE
CHECK:	Bill Lin	12/28'23	SHEET: 3/4
APPROVAL:			SCALE: 1:1 UNIT: mm

REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A			INITIAL ISSUE	12/28'23	Joe Lam



HARD TRAY VIEW

4.35kg	1.86kg	32	10	320
GROSS WEIGHT	NET WEIGHT	PCS/ TRAY	TRAY/ BOX	PCS/ BOX



DIM	TOL	DIM	TOL
.x	±1.00	.x	
.X	±0.50	.X	
.XX	±0.35		



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C-DWG:	TY	DATE	TITLE: DDR4 288PIN SMT BIG EXTRACTOR SOLDER TAB
DESIGN:	Joe Lam	12/28'23	P/N: SEE P/N INFORMATION
CHECK:	Mike Chen	12/28'23	SHEET: 4/4
APPROVAL:	Bill Lin	12/28'23	SCALE: 1:1 UNIT: mm

DRAW NO. SC2107184-1